

PCN Number:	20160426000	PCN Date:	6/9/2016
Title:	Datasheet for MSP430FR5738		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

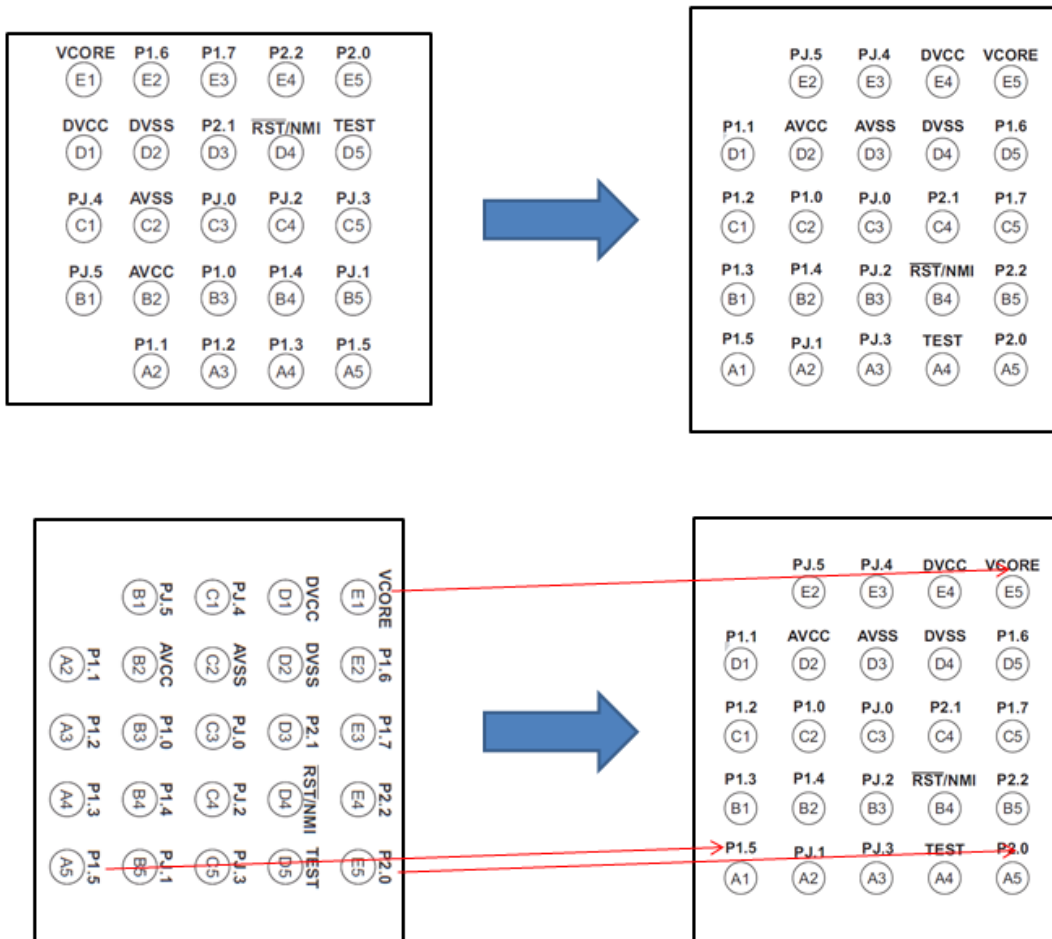
Notification Details

Description of Change:

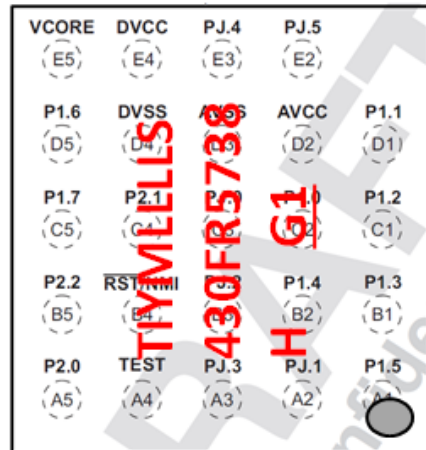
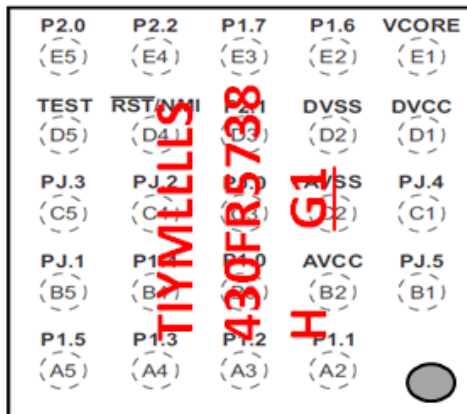
Texas Instruments Incorporated is announcing an information only notification.

Beyond other datasheet changes, the important change to note is the change in the drawing of the DSBGA:

Datasheet Update: Drawing is rotated by 90DEG and ball numbers are adjusted



Top View of Package: Sympo Change



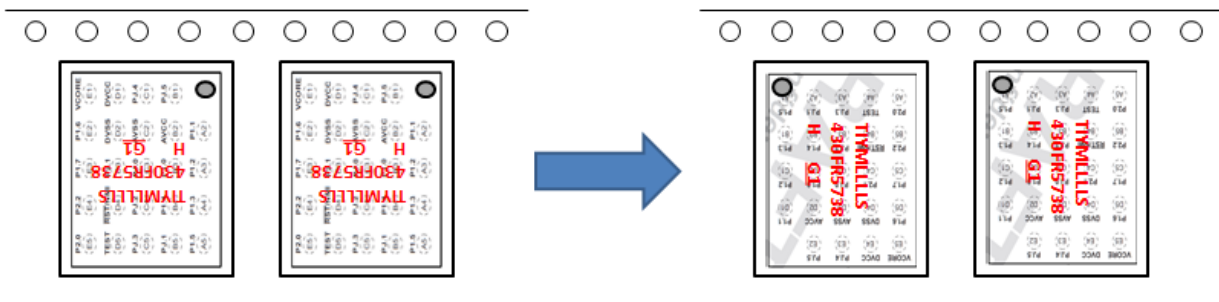
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+-----+
|         |
| TIYMLLLS |
| 430FR5738 |
| # G1 |
|!0 |
+-----+
0 - PIN A1
(FILLED SOLID)
    
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TI = TI LETTERS
YM = YEAR MONTH DATE CODE
LLL = LOT TRACE CODE
S = ASSEMBLY SITE CODE PER QSS 005-120
# = DIE REVISION
# = MUST BE SYMBOLIZED WITH
AN UNDERSCORE
    
```

Tape and Reel needs to change: Device rotated 180DEG in Pocket



NOTE: Requirement: Pin1 (A1) Marker needs to be at punch row side

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



MSP430FR5739, MSP430FR5738, MSP430FR5737, MSP430FR5736, MSP430FR5735
MSP430FR5734, MSP430FR5733, MSP430FR5732, MSP430FR5731, MSP430FR5730

SLAS639K – JULY 2011 – REVISED APRIL 2016

Changes from June 15, 2014 to April 25, 2016

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• Added Section 3.1, Related Products	6
• Changed all ball coordinates on YQD package (rotated package relative to prior orientation)	9
• Changed all ball coordinates for the YQD package in Table 4-1, Signal Descriptions	10
• Moved T_{stg} to Absolute Maximum Ratings , and removed Handling Ratings table.....	15
• Added Section 5.2, ESD Ratings	15
• Added Section 5.6, Thermal Resistance Characteristics	18
• Changed the note that starts "Tools that access the Spy-Bi-Wire and BSL interfaces..."	38
• Changed all cases of "bootstrap loader" to "bootloader".....	48
• Corrected spelling of NMIIFG in Table 6-6, System Module Interrupt Vector Registers	51
• Changed ball coordinates for the YQD package in Table 6-8, TA0 Signal Connections	53
• Changed ball coordinates for the YQD package in Table 6-9, TA1 Signal Connections	54
• Changed ball coordinates for the YQD package in Table 6-10, TB0 Signal Connections	55
• Moved and changed the title of Section 6.11, Input/Output Diagrams	69
• Switched P1SEL0.x and P1SEL1.x in P1.0 to P1.2 schematic to show correct inputs to multiplexers.....	69
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• Switched PJSEL0.4 and PJSEL1.4 in PJ.4 schematic to show correct inputs to multiplexers	87
• Switched PJSEL0.5 and PJSEL1.5 in PJ.5 schematic to show correct inputs to multiplexers	88
• Moved Section 6.12, Device Descriptors (TLV)	89
• Replaced former section Development Tools Support with Section 7.3, Tools and Software	94
• Updated Section 7.4, Documentation Support	96

The datasheet number will be changing.

Device Family	Change From:	Change To:
MSP430FR5738	SLAS639J	SLAS639K

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/MSP430FR5738>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

MSP430FR5738IYQDR	MSP430FR5738IYQDT		
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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